

Global 3D IC and 2.5D IC Packaging Market 2024 by Manufacturers, Regions, Type and Application, Forecast to 2030

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Abstracts

According to our (Global Info Research) latest study, the global 3D IC and 2.5D IC Packaging market size was valued at USD 102920 million in 2023 and is forecast to a readjusted size of USD 263040 million by 2030 with a CAGR of 14.3% during review period.

Following a strong growth of 26.2 percent in the year 2021, WSTS revised it down to a single digit growth for the worldwide semiconductor market in 2022 with a total size of US\$580 billion, up 4.4 percent. WSTS lowered growth estimation as inflation rises and end markets seeing weaker demand, especially those exposed to consumer spending. While some major categories are still double-digit year-over-year growth in 2022, led by Analog with 20.8 percent, Sensors with 16.3 percent, and Logic with 14.5 percent growth. Memory declined with 12.6 percent year over year. In 2022, all geographical regions showed double-digit growth except Asia Pacific. The largest region, Asia Pacific, declined 2.0 percent. Sales in the Americas were US\$142.1 billion, up 17.0% year-on-year, sales in Europe were US\$53.8 billion, up 12.6% year-on-year, and sales in Japan were US\$48.1 billion, up 10.0% year-on-year. However, sales in the largest Asia-Pacific region were US\$336.2 billion, down 2.0% year-on-year.

The Global Info Research report includes an overview of the development of the 3D IC and 2.5D IC Packaging industry chain, the market status of Logic (3D Wafer-level Chip-scale Packaging, 3D TSV), Imaging & Optoelectronics (3D Wafer-level Chip-scale Packaging, 3D TSV), and key enterprises in developed and developing market, and analysed the cutting-edge technology, patent, hot applications and market trends of 3D IC and 2.5D IC Packaging.

Regionally, the report analyzes the 3D IC and 2.5D IC Packaging markets in key regions. North America and Europe are experiencing steady growth, driven by government initiatives and increasing consumer awareness. Asia-Pacific, particularly China, leads the global 3D IC and 2.5D IC Packaging market, with robust domestic demand, supportive policies, and a strong manufacturing base.

Key Features:

The report presents comprehensive understanding of the 3D IC and 2.5D IC Packaging market. It provides a holistic view of the industry, as well as detailed insights into individual components and stakeholders. The report analysis market dynamics, trends, challenges, and opportunities within the 3D IC and 2.5D IC Packaging industry.

The report involves analyzing the market at a macro level:

Market Sizing and Segmentation: Report collect data on the overall market size, including the sales quantity (K Units), revenue generated, and market share of different by Type (e.g., 3D Wafer-level Chip-scale Packaging, 3D TSV).

Industry Analysis: Report analyse the broader industry trends, such as government policies and regulations, technological advancements, consumer preferences, and market dynamics. This analysis helps in understanding the key drivers and challenges influencing the 3D IC and 2.5D IC Packaging market.

Regional Analysis: The report involves examining the 3D IC and 2.5D IC Packaging market at a regional or national level. Report analyses regional factors such as government incentives, infrastructure development, economic conditions, and consumer behaviour to identify variations and opportunities within different markets.

Market Projections: Report covers the gathered data and analysis to make future projections and forecasts for the 3D IC and 2.5D IC Packaging market. This may include estimating market growth rates, predicting market demand, and identifying emerging trends.

The report also involves a more granular approach to 3D IC and 2.5D IC Packaging:

Company Analysis: Report covers individual 3D IC and 2.5D IC Packaging manufacturers, suppliers, and other relevant industry players. This analysis includes studying their financial performance, market positioning, product portfolios,

partnerships, and strategies.

Consumer Analysis: Report covers data on consumer behaviour, preferences, and attitudes towards 3D IC and 2.5D IC Packaging. This may involve surveys, interviews, and analysis of consumer reviews and feedback from different by Application (Logic, Imaging & Optoelectronics).

Technology Analysis: Report covers specific technologies relevant to 3D IC and 2.5D IC Packaging. It assesses the current state, advancements, and potential future developments in 3D IC and 2.5D IC Packaging areas.

Competitive Landscape: By analyzing individual companies, suppliers, and consumers, the report presents insights into the competitive landscape of the 3D IC and 2.5D IC Packaging market. This analysis helps understand market share, competitive advantages, and potential areas for differentiation among industry players.

Market Validation: The report involves validating findings and projections through primary research, such as surveys, interviews, and focus groups.

Market Segmentation

3D IC and 2.5D IC Packaging market is split by Type and by Application. For the period 2019-2030, the growth among segments provides accurate calculations and forecasts for consumption value by Type, and by Application in terms of volume and value.

Market segment by Type

3D Wafer-level Chip-scale Packaging

3D TSV

2.5D

Market segment by Application

Logic

Imaging & Optoelectronics

Memory

MEMS/Sensors

LED

Power

Major players covered

Taiwan Semiconductor

Samsung Electronics

Toshiba Corp

Advanced Semiconductor Engineering

Amkor Technology

Market segment by region, regional analysis covers

North America (United States, Canada and Mexico)

Europe (Germany, France, United Kingdom, Russia, Italy, and Rest of Europe)

Asia-Pacific (China, Japan, Korea, India, Southeast Asia, and Australia)

South America (Brazil, Argentina, Colombia, and Rest of South America)

Middle East & Africa (Saudi Arabia, UAE, Egypt, South Africa, and Rest of Middle East & Africa)

The content of the study subjects, includes a total of 15 chapters:

Chapter 1, to describe 3D IC and 2.5D IC Packaging product scope, market overview, market estimation caveats and base year.

Chapter 2, to profile the top manufacturers of 3D IC and 2.5D IC Packaging, with price, sales, revenue and global market share of 3D IC and 2.5D IC Packaging from 2019 to 2024.

Chapter 3, the 3D IC and 2.5D IC Packaging competitive situation, sales quantity, revenue and global market share of top manufacturers are analyzed emphatically by landscape contrast.

Chapter 4, the 3D IC and 2.5D IC Packaging breakdown data are shown at the regional level, to show the sales quantity, consumption value and growth by regions, from 2019 to 2030.

Chapter 5 and 6, to segment the sales by Type and application, with sales market share and growth rate by type, application, from 2019 to 2030.

Chapter 7, 8, 9, 10 and 11, to break the sales data at the country level, with sales quantity, consumption value and market share for key countries in the world, from 2017 to 2023. and 3D IC and 2.5D IC Packaging market forecast, by regions, type and application, with sales and revenue, from 2025 to 2030.

Chapter 12, market dynamics, drivers, restraints, trends and Porters Five Forces analysis.

Chapter 13, the key raw materials and key suppliers, and industry chain of 3D IC and 2.5D IC Packaging.

Chapter 14 and 15, to describe 3D IC and 2.5D IC Packaging sales channel, distributors, customers, research findings and conclusion.

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